

Features

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology
- ★ 100% EAS Guaranteed

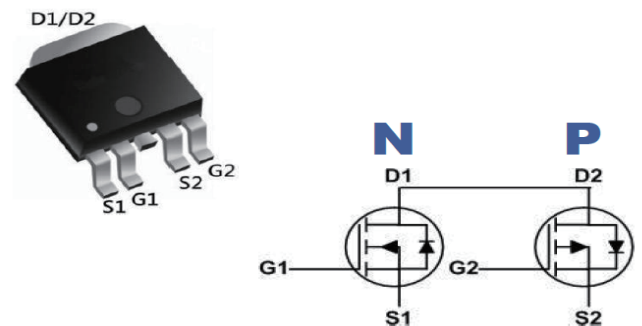
Product Summary

| BVDSS | RDSON | ID |
|-------|-------|------|
| 30V | 15mΩ | 20A |
| -30V | 25mΩ | -23A |

Description

The 3020 is the high performance complementary N-ch and P-ch MOSFETs with high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications. The 3020 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

TO252-4 Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | | Units |
|---------------------------------------|--|------------|------------|-------|
| | | N-Ch | P-Ch | |
| V _{DS} | Drain-Source Voltage | 30 | -30 | V |
| V _{GS} | Gate-Source Voltage | ±20 | ±20 | V |
| I _D @T _C =25°C | Continuous Drain Current, V _{GS} @ 10V ¹ | 20 | -23 | A |
| I _b @T _C =100°C | Continuous Drain Current, V _{GS} @ 10V ¹ | 15 | -14 | A |
| I _{DM} | Pulsed Drain Current ² | 60 | -60 | A |
| EAS | Single Pulse Avalanche Energy ³ | 26.6 | 38 | mJ |
| P _D @T _C =25°C | Total Power Dissipation ⁴ | 20.8 | 20.8 | W |
| P _D @T _A =25°C | Total Power Dissipation ⁴ | 2 | 2 | W |
| T _{STG} | Storage Temperature Range | -55 to 150 | -55 to 150 | °C |
| T _J | Operating Junction Temperature Range | -55 to 150 | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R _{θJA} | Thermal Resistance Junction-Ambient ¹ | --- | 62 | °C/W |
| R _{θJC} | Thermal Resistance Junction-Case ¹ | --- | 6 | °C/W |

N-Channel Electrical Characteristics $T_J=25^\circ\text{C}$ unless otherwise specified

| Symbol | Parameter | Test condition | Min. | Typ. | Max. | Units |
|------------------------------|--|--|------|-------|-----------|---------------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=250\mu A$ | 30 | --- | --- | V |
| $\Delta BV_{DSS}/\Delta T_J$ | BVDSS Temperature Coefficient | Reference to 25°C , $I_D=1\text{mA}$ | --- | 0.023 | --- | $V/^\circ\text{C}$ |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance ² | $V_{GS}=10V, I_D=10A$ | --- | 15 | 20 | $m\Omega$ |
| | | $V_{GS}=4.5V, I_D=6A$ | --- | 20 | 25 | |
| $V_{GS(th)}$ | Gate Threshold Voltage | | 1 | --- | 2.5 | V |
| $\Delta V_{GS(th)}$ | $V_{GS(th)}$ Temperature Coefficient | $V_{GS}=V_{DS}, I_D=250\mu A$ | --- | -4.2 | --- | $mV/^\circ\text{C}$ |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS}=24V, V_{GS}=0V, T_J=25^\circ\text{C}$ | --- | --- | 1 | μA |
| | | $V_{DS}=24V, V_{GS}=0V, T_J=55^\circ\text{C}$ | --- | --- | 5 | |
| I_{GSS} | Gate-Source Leakage Current | $V_{GS}=\pm 20V, V_{DS}=0V$ | --- | --- | ± 100 | nA |
| g_{fs} | Forward Transconductance | $V_{DS}=5V, I_D=10A$ | --- | 14 | --- | S |
| R_g | Gate Resistance | $V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$ | --- | 2.3 | --- | Ω |
| Q_g | Total Gate Charge (4.5V) | | --- | 5 | --- | nC |
| Q_{gs} | Gate-Source Charge | $V_{DS}=20V, V_{GS}=4.5V, I_D=10A$ | --- | 1.11 | --- | |
| Q_{gd} | Gate-Drain Charge | | --- | 2.61 | --- | |
| $T_{d(on)}$ | Turn-On Delay Time | | --- | 7.7 | --- | ns |
| T_r | Rise Time | $V_{DD}=12V, V_{GS}=10V,$ $R_G=3.3\Omega, I_D=6A$ | --- | 46 | --- | |
| $T_{d(off)}$ | Turn-Off Delay Time | | --- | 11 | --- | |
| T_f | Fall Time | | --- | 3.6 | --- | |
| C_{iss} | Input Capacitance | | --- | 416 | --- | pF |
| C_{oss} | Output Capacitance | $V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$ | --- | 62 | --- | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 51 | --- | |

Diode Characteristics

| Symbol | Parameter | Test condition | Min. | Typ. | Max. | Units |
|----------|--|---|------|------|------|-------|
| I_S | Continuous Source Current ^{1,5} | $V_G=V_D=0V$, Force Current | --- | --- | 20 | A |
| I_{SM} | Pulsed Source Current ^{2,5} | | --- | --- | 40 | A |
| V_{SD} | Diode Forward Voltage ² | $V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$ | --- | --- | 1.2 | V |

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=20A$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

P-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | Test condition | Min. | Typ. | Max. | Units |
|------------------------------|--|---|------|--------|-----------|----------------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=-250\mu A$ | -30 | --- | --- | V |
| $\Delta BV_{DSS}/\Delta T_J$ | BV_{DSS} Temperature Coefficient | Reference to 25°C , $I_D=-1\text{mA}$ | --- | -0.021 | --- | $V/^\circ\text{C}$ |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance ² | $V_{GS}=-10V, I_D=-8A$ | --- | 25 | 30 | m Ω |
| | | $V_{GS}=-4.5V, I_D=-6A$ | --- | 30 | 35 | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS}=V_{DS}, I_D=-250\mu A$ | -1 | --- | -2.5 | V |
| $\Delta V_{GS(th)}$ | $V_{GS(th)}$ Temperature Coefficient | | --- | -4.2 | --- | mV/ $^\circ\text{C}$ |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS}=-24V, V_{GS}=0V, T_J=25^\circ\text{C}$ | --- | --- | 1 | μA |
| | | $V_{DS}=-24V, V_{GS}=0V, T_J=55^\circ\text{C}$ | --- | --- | 5 | |
| I_{GSS} | Gate-Source Leakage Current | $V_{GS}=\pm 20V, V_{DS}=0V$ | --- | --- | ± 100 | nA |
| g_{fs} | Forward Transconductance | $V_{DS}=-5V, I_D=-8A$ | --- | 12.6 | --- | S |
| R_g | Gate Resistance | $V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$ | --- | 15 | --- | Ω |
| Q_g | Total Gate Charge (-4.5V) | | --- | 9.8 | --- | nC |
| Q_{gs} | Gate-Source Charge | $V_{DS}=-20V, V_{GS}=-4.5V, I_D=-6A$ | --- | 2.2 | --- | |
| Q_{gd} | Gate-Drain Charge | | --- | 3.4 | --- | |
| $T_{d(on)}$ | Turn-On Delay Time | | --- | 16.4 | --- | ns |
| T_r | Rise Time | $V_{DD}=-24V, V_{GS}=-10V,$ $R_G=3.3\Omega, I_D=-1A$ | --- | 20.2 | --- | |
| $T_{d(off)}$ | Turn-Off Delay Time | | --- | 55 | --- | |
| T_f | Fall Time | | --- | 10 | --- | |
| C_{iss} | Input Capacitance | | --- | 930 | --- | pF |
| C_{oss} | Output Capacitance | $V_{DS}=-15V, V_{GS}=0V, f=1\text{MHz}$ | --- | 148 | --- | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 115 | --- | |

Diode Characteristics

| Symbol | Parameter | Test condition | Min. | Typ. | Max. | Units |
|----------|--|--|------|------|------|-------|
| I_S | Continuous Source Current ^{1,5} | $V_G=V_D=0V$, Force Current | --- | --- | -23 | A |
| I_{SM} | Pulsed Source Current ^{2,5} | | --- | --- | -35 | A |
| V_{SD} | Diode Forward Voltage ² | $V_{GS}=0V, I_S=-1A, T_J=25^\circ\text{C}$ | --- | --- | -1.2 | V |

Note :

- The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper. 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- The EAS data shows Max. rating . The test condition is $V_{DD}=-25V, V_{GS}=-10V, L=0.1\text{mH}, I_{AS}=-30A$
- The power dissipation is limited by 150°C junction temperature
- The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

N-Channel Typical Performance Characteristics

Figure 1: Output Characteristics

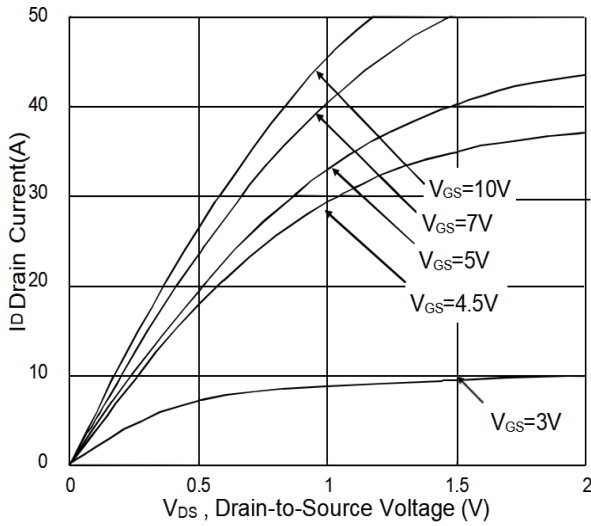


Figure 2: On-Resistance vs. Gate-Source

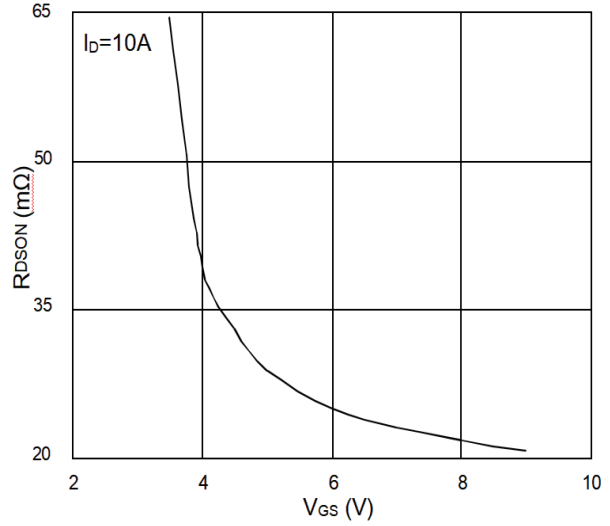


Figure 3: Forward Characteristics Of Reverse

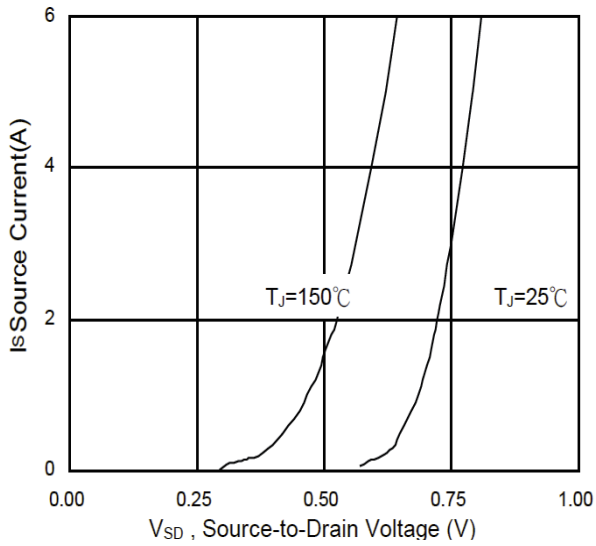


Figure 4: Gate-Charge Characteristics

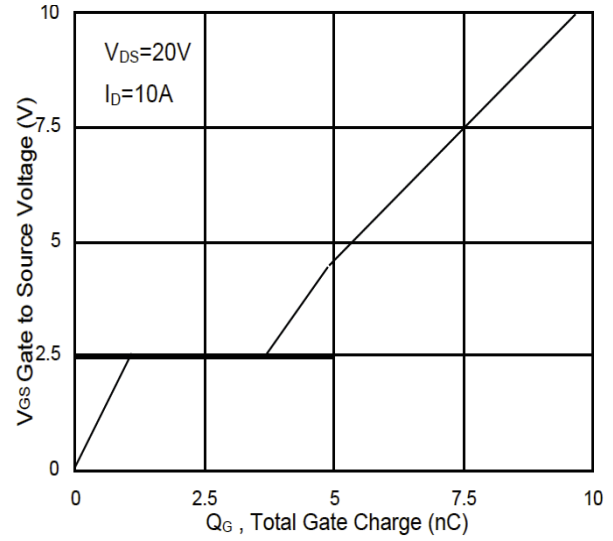


Figure 5: Normalized VGS(th) vs. TJ

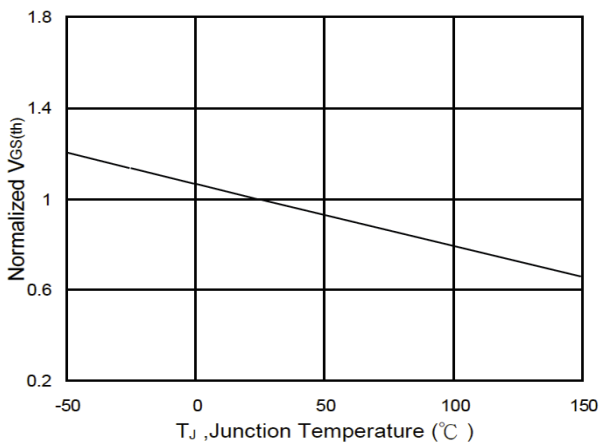
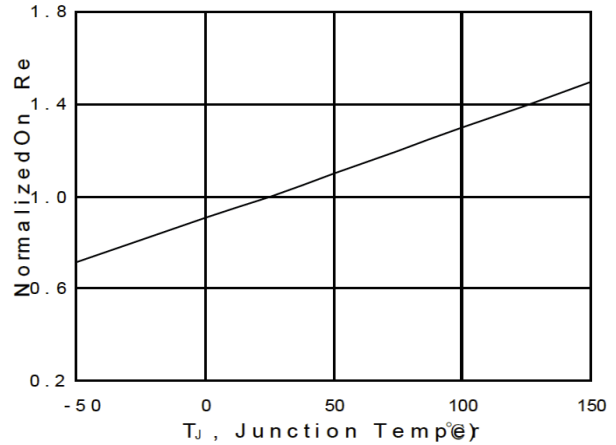


Figure 6: Normalized RDS(on) vs. TJ



N-Channel Typical Performance Characteristics

Figure7:Capacitance

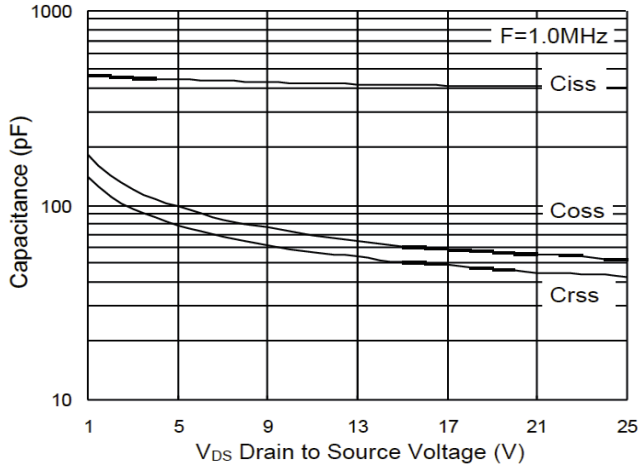


Figure 8 Safe Operating Area

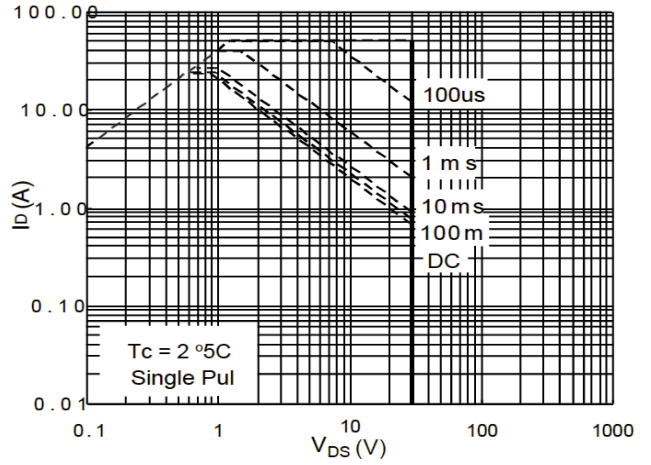


Figure9:Normalized Maximum Transient Thermal Impedance

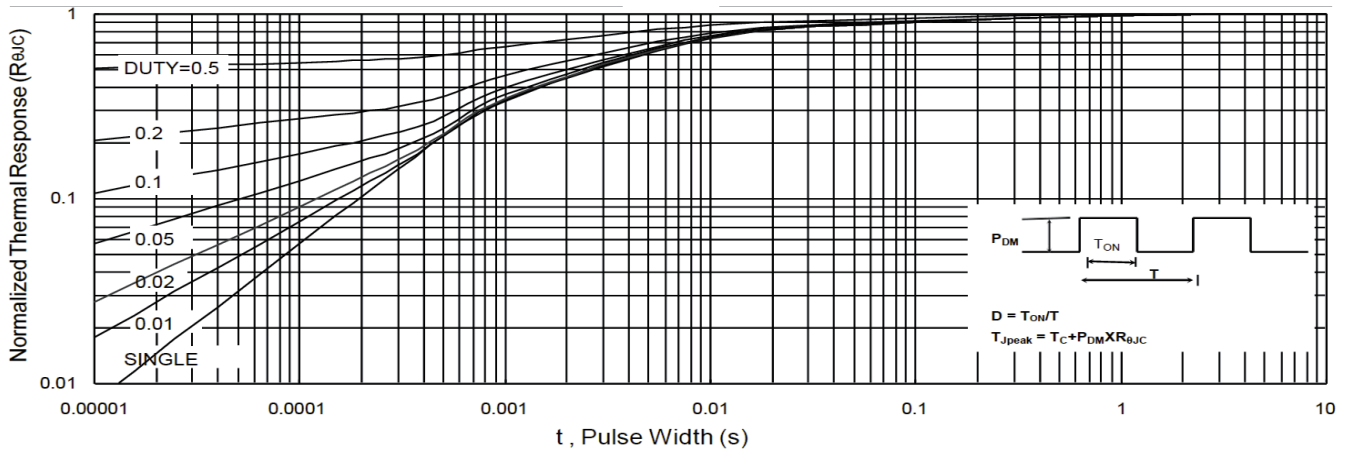


Figure10:Switching Time Waveform

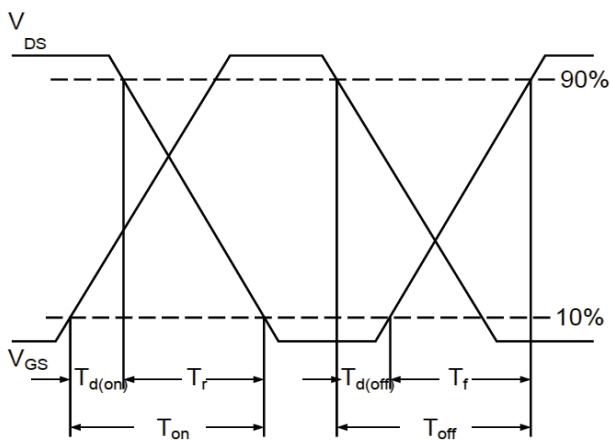
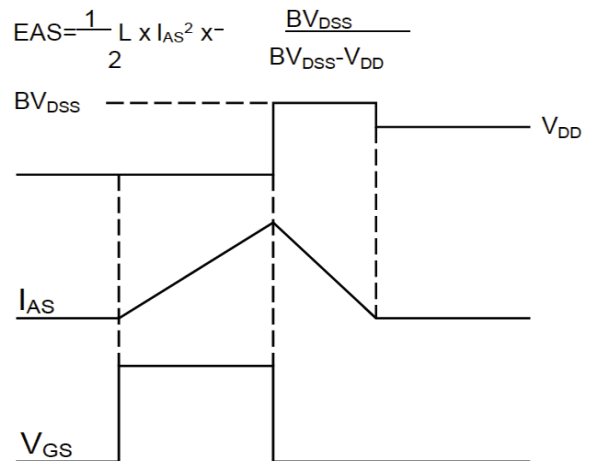


Figure11:Unclamped Inductive Switching



$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

P-Channel Typical Performance Characteristics

Figure1:Capacitance

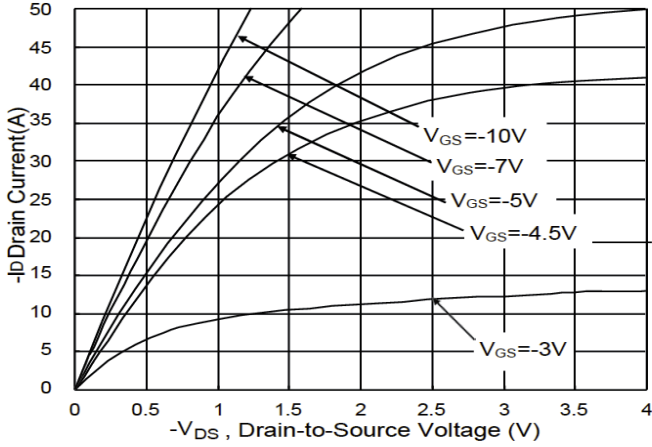


Figure 2:On-Resistance v.s Gate-Source

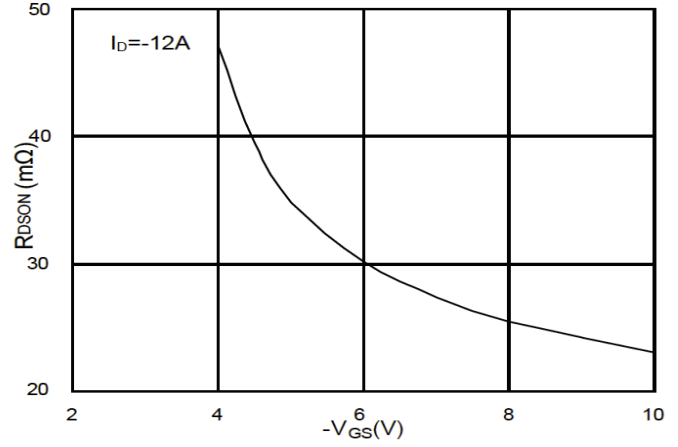


Figure3:Forward Characteristics Of Reverse

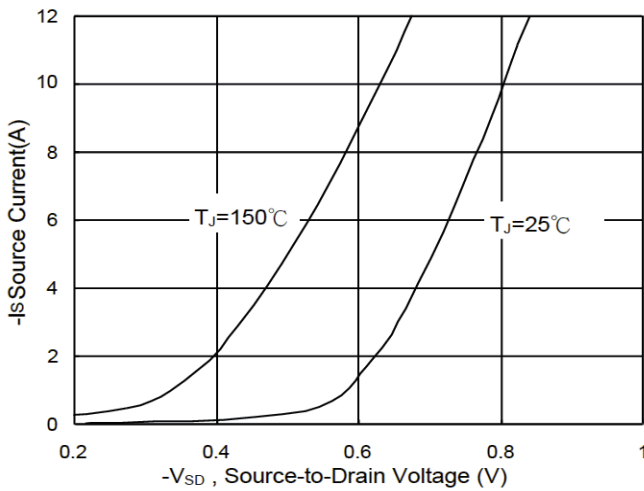


Figure4:Gate-Charge Characteristics

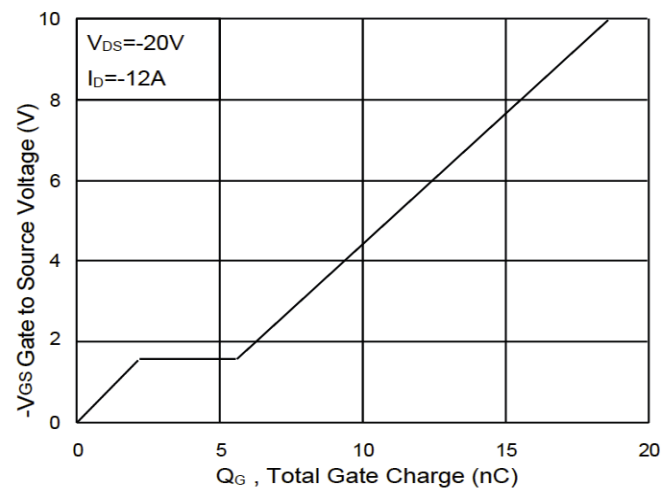


Figure5:Normalized VGS(th) v.s TJ

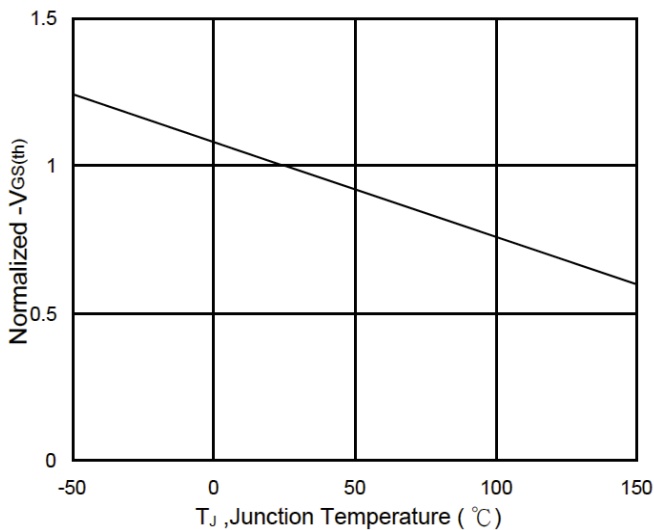
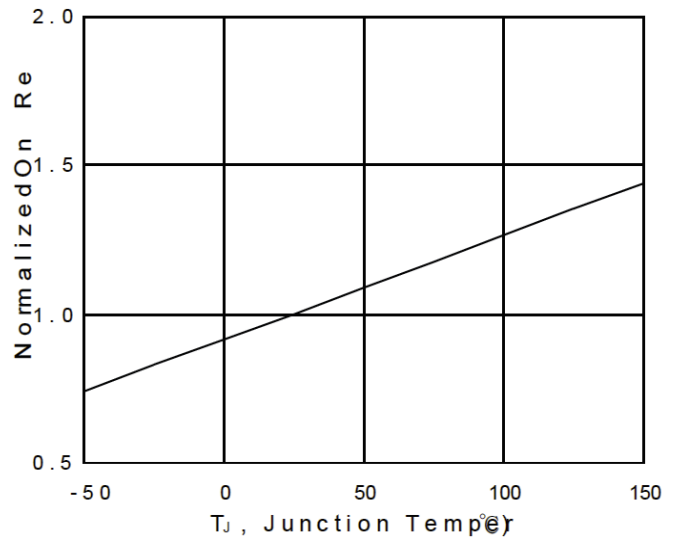


Figure 6:Normalized RDS(on) v.s TJ



P-Channel Typical Performance Characteristics

Figure 7: Capacitance

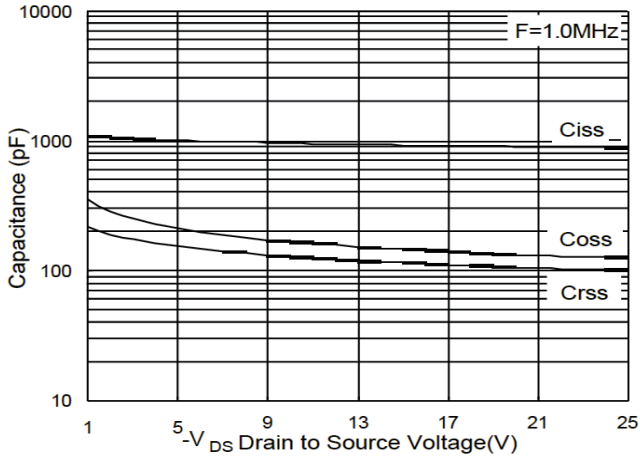


Figure 8: Safe Operating Areare

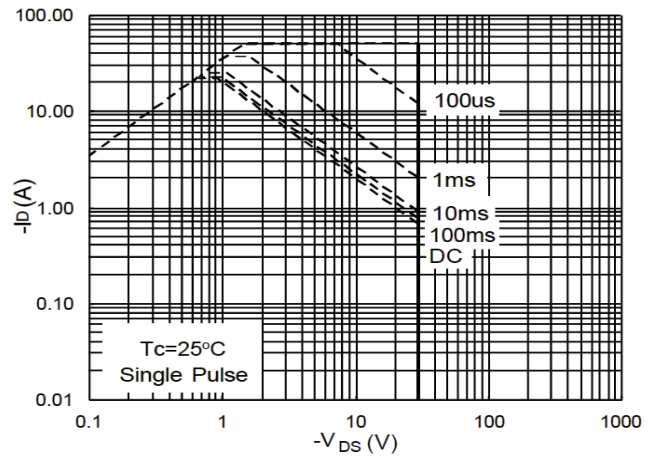


Figure 9: Normalized Maximum Transient

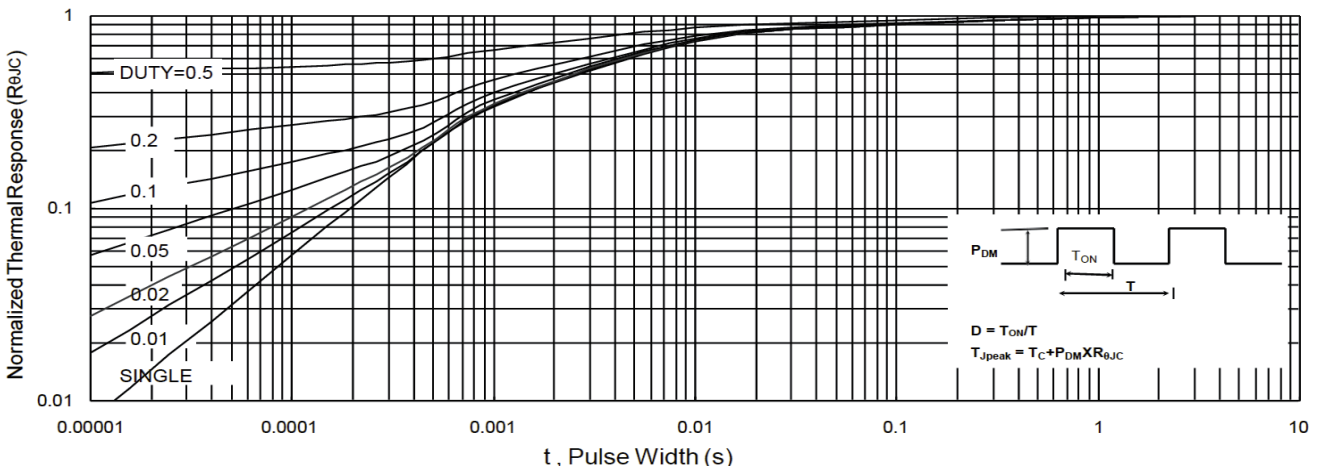


Figure 10: Switching Time Waveformse

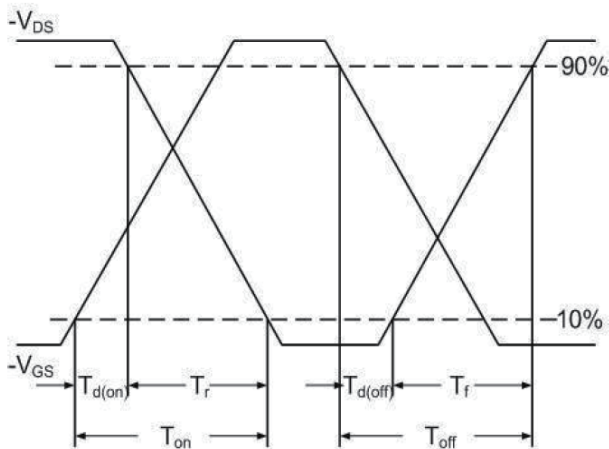
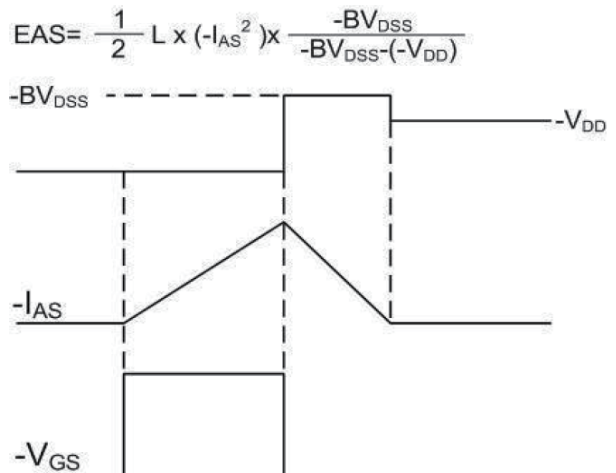
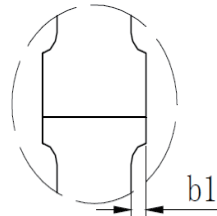
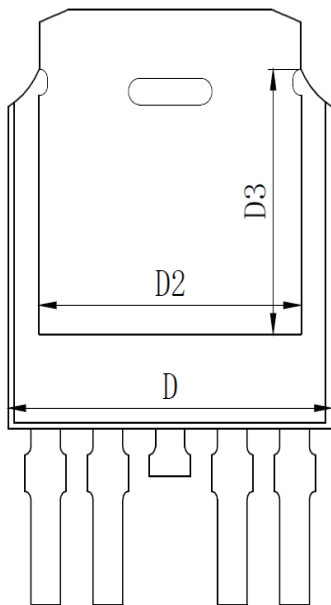
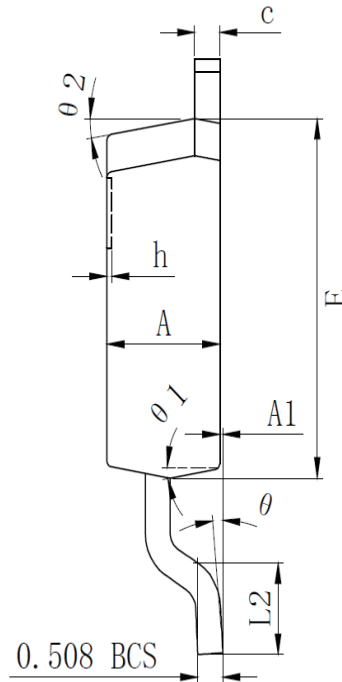
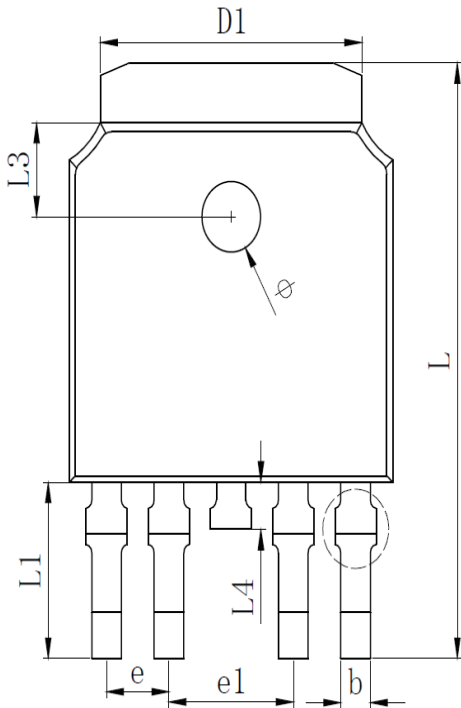


Figure 11: Unclamped Inductive Switching



Mechanical Dimensions for TO-252-4L



| SYMBOL | MILLIMETER | | |
|------------|------------|--------|--------|
| | MIN | Typ. | MAX |
| A | 2.200 | 2.300 | 2.400 |
| A1 | 0.000 | | 0.127 |
| b | 0.550 | 0.600 | 0.650 |
| b1 | 0.000 | | 0.120 |
| c(电镀后) | 0.460 | 0.520 | 0.580 |
| D | 6.500 | 6.600 | 6.700 |
| D1 | 5.334 REF | | |
| D2 | 5.346 REF | | |
| D3 | 4.490 REF | | |
| E | 6.000 | 6.100 | 6.200 |
| e | 1.270 TYP | | |
| e1 | 2.540 TYP | | |
| h | 0.000 | 0.100 | 0.200 |
| L | 9.900 | 10.100 | 10.300 |
| L1 | 2.988 REF | | |
| L2 | 1.400 | 1.550 | 1.700 |
| L3 | 1.600 REF | | |
| L4 | 0.700 | 0.800 | 0.900 |
| Φ | 1.100 | 1.200 | 1.300 |
| θ | 0° | | 8° |
| $\theta 1$ | 9° TYP | | |
| $\theta 2$ | 9° TYP | | |

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